

a first suspension lead for supporting said semiconductor chip, extending in a first direction;

a second suspension lead for supporting said semiconductor chip, extending in a second direction which is different from said first direction, said second suspension lead intersecting said first suspension lead; and

a plurality of leads each having an inner lead and an outer lead which is continuously formed with said inner lead, said plurality of leads being arranged to surround an intersecting portion of said first and second suspension leads;

(3) a plurality of bonding wires electrically connecting said inner leads of said plurality of leads with said plurality of bonding pads, respectively; and

(4) a resin body sealing said semiconductor chip, said inner leads of said plurality of leads, said first and second suspension leads and said plurality of bonding wires;

wherein said semiconductor chip is disposed on said intersecting portion of said first and second suspension leads,

wherein a width of each of said first and second suspension leads at the vicinity of said intersecting portion is wider than that of each said first and second suspension leads at vicinities beyond said semiconductor chip, and

wherein said rear surface of said semiconductor chip is fixed to said first and second suspension leads at the vicinity of said intersecting point by an adhesive.

51 64. A semiconductor device according to claim 63, wherein said first and second suspension leads intersect each other at a substantially right angle.

65. A semiconductor device according to claim 64, wherein said resin body has a tetragonal shape, wherein said outer leads of said plurality of leads protrude outwardly from four sides of said resin body, and wherein said first and second suspension leads extend from said intersecting portion toward four corners of said resin body.

66. A semiconductor device according to claim 63, wherein a portion of said rear surface of said semiconductor chip is adhered to said intersecting portion of said first and second suspension leads, and wherein another portion of said rear surface of said semiconductor chip is contacted with said resin body.

ai 67. A semiconductor device according to claim 64, wherein said semiconductor chip has a tetragonal shape, and wherein said wider portion at the vicinity of said intersecting portion of said first and second suspension leads extends from a central portion of said rear surface of said semiconductor chip toward four corners of said semiconductor chip.

68. A semiconductor device comprising:

(1) a semiconductor chip having a main surface and a rear surface opposite to said main surface, said semiconductor chip having a plurality of semiconductor elements and bonding pads formed on said main surface;

(2) a lead frame including:

a chip mounting portion for mounting said semiconductor chip;

a plurality of suspension leads which are continuously formed with said chip mounting portion; and

a plurality of leads each having an inner lead and an outer lead which is continuously formed with said inner lead, said plurality of leads being arranged to surround said chip mounting portion;

(3) a plurality of bonding wires electrically connecting said inner leads of said plurality of leads with said plurality of bonding pads, respectively; and

(4) a resin body sealing said semiconductor chip, said inner leads of said plurality of leads, said chip mounting portion, said plurality of suspension leads and said plurality of bonding wires;

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wherein said chip mounting portion has a first portion extending in a first direction and a second portion extending in a second direction which is a different direction from said first direction, said second portion intersecting said first portion,

wherein a width of each of said first and second portions of said chip mounting portion is wider than that of each of said plurality of suspension leads,

wherein both ends of each of said first and second portions of said chip mounting portion are coupled with said plurality of suspension leads respectively,

wherein an intersecting portion of said first and second portions of said chip mounting portion is located at a substantially central portion of said rear surface of said semiconductor chip,

wherein said both ends of each of said first and second portions of said chip mounting portion are located at the peripheral portions of said rear surface of said semiconductor chip, and

wherein said rear surface of said semiconductor chip is fixed to said chip mounting portion at both of said central and peripheral portions of said rear surface of said semiconductor chip by an adhesive.

69. A semiconductor device according to claim 68, wherein said first and second directions intersect each other at a substantially right angle.

a/ 70. A semiconductor device according to claim 69, wherein said resin body has a tetragonal shape, wherein said outer leads of said plurality of leads protrude outwardly from four sides of said resin body, and wherein said plurality of suspension leads extend from said both ends of said first and second portions of said chip mounting portion toward four corners of said resin body.

71. A semiconductor device according to claim 68, wherein a portion of said rear surface of said semiconductor chip is adhered to said first and second portions of said chip mounting portion, and wherein another portion of said rear surface of said semiconductor chip is contacted with said resin body.

72. A semiconductor device according to claim 71, wherein said semiconductor chip has a tetragonal shape, and wherein said both ends of each of said first and second portions are located at the vicinity of four corners of said semiconductor chip. - -